

## COOLING OF SMALL FORM FACTOR AND 19" SYSTEMS

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### Smart cooling

Increasing packing densities and power levels lead to intensified heat generation. However, this intensified heat generation can increase the risk of failure of electronic devices and systems. Sophisticated cooling concepts are necessary to avoid thermal overloads and ensure trouble-free operation of the components. To optimize a perfect cooling effect, various factors must be considered, depending on the application and area of use.

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### This white paper approaches fundamental criteria such as:

- The performance or power dissipation of the application
- The ambient temperature
- The required IP protection and EMC protection
- The noise level, the reliability, and the desired durability of the systems



### Four types of cooling techniques are typically available for this purpose:

- Free convection
- Forced convection
- Conduction cooling
- Water/liquid cooling

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